

**SANYO**

No. ✕ 4541B

**LC331632M-70/80/10/12****512 K (32768 words × 16 bits) Pseudo-SRAM**

## Preliminary

### Overview

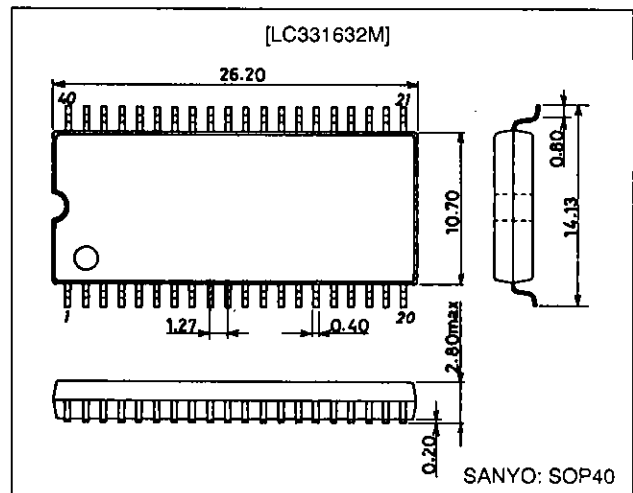
The LC331632 series is composed of pseudo static RAM that operate on a single 5 V power supply and are organized as 32768 words × 16 bits. By using memory cells each composed of a single transistor and capacitor, together with peripheral CMOS circuitry, this series achieves ease of use with high density, high speed, and low power dissipation. The LC331632 series can easily accomplish auto-refresh by means of  $\overline{LOE}/\overline{RFSH}$  input. The available package is the 40-pin SOP with a width of 525 mil.

### Features

- 32768 words × 16 bits configuration
- $\overline{CE}$  access time/ $\overline{OE}$  access time/Cycle time/Current dissipation

### Package Dimensions

unit: mm

**3195-SOP40**

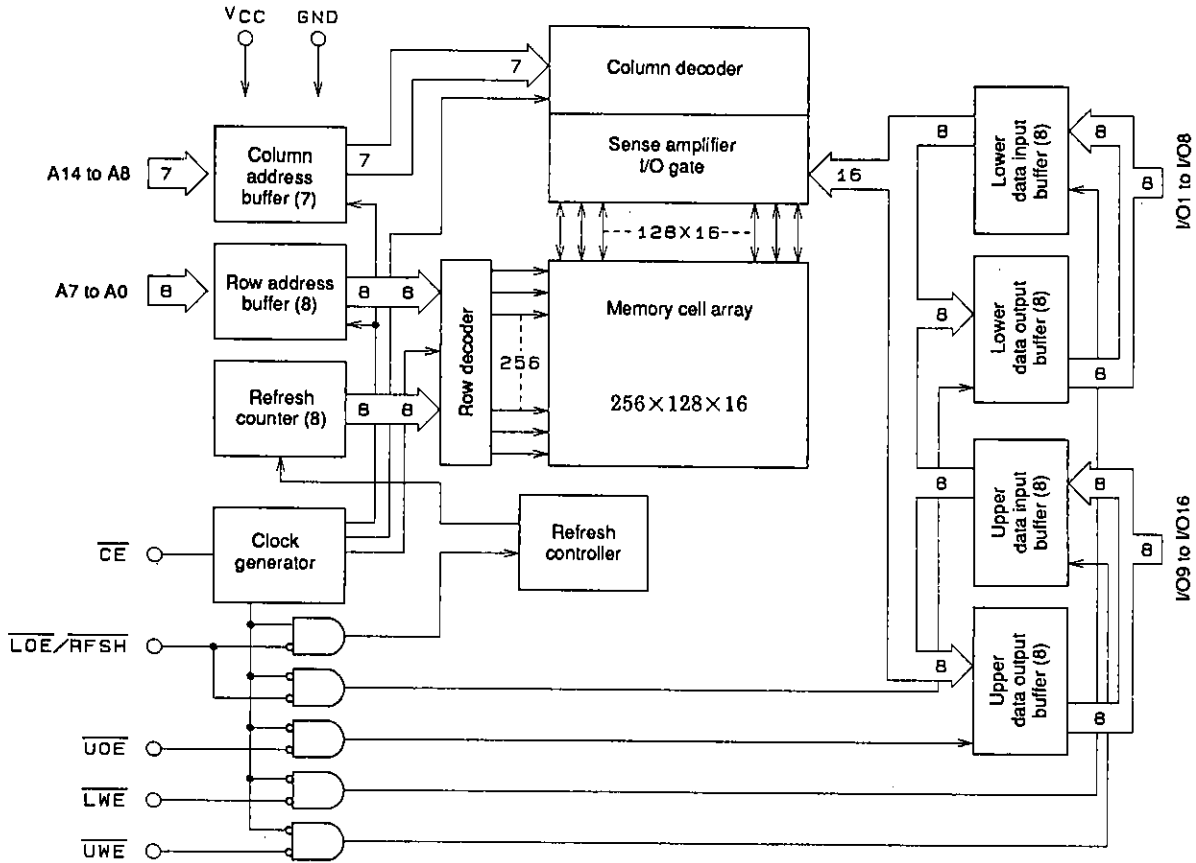
| Parameter                   | LC331632M |        |        |        |
|-----------------------------|-----------|--------|--------|--------|
|                             | -70       | -80    | -10    | -12    |
| $\overline{CE}$ access time | 70 ns     | 80 ns  | 100 ns | 120 ns |
| $\overline{OE}$ access time | 35 ns     | 40 ns  | 50 ns  | 75 ns  |
| Cycle time                  | 115 ns    | 130 ns | 160 ns | 210 ns |
| Current dissipation         | Operating | 100 mA | 90 mA  | 75 mA  |
|                             | Standby   | 2 mA   |        |        |

- Single 5 V  $\pm 10\%$  power supply
- All input and output (I/O) TTL compatible
- Fast access time and low power dissipation
- 4 ms refresh using 256 refresh cycles
- Supports  $\overline{CE}$ -only refresh and auto-refresh
- Supports byte unit read and write operations using the  $\overline{LOE}/\overline{RFSH}$  and  $\overline{UOE}$  inputs or the  $\overline{LWE}$  and  $\overline{UWE}$  inputs.
- Package  
SOP 40-pin (525 mil) plastic package: LC331632M

**SANYO Electric Co., Ltd. Semiconductor Business Headquarters**

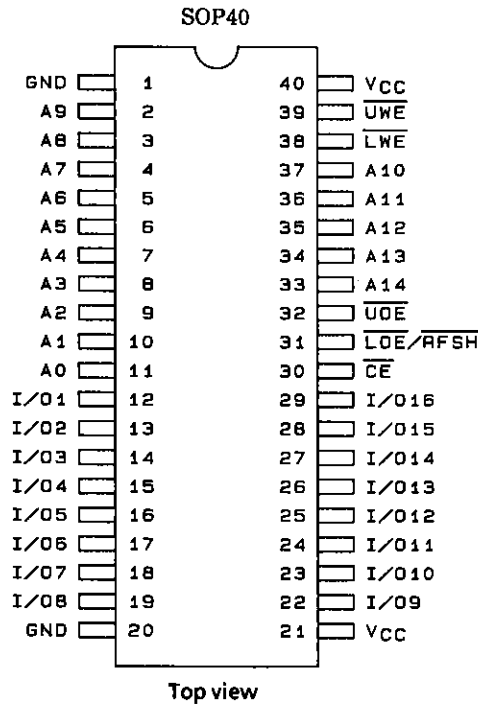
TOKYO OFFICE Tokyo Bldg., 1-10, 1 Chome, Ueno, Taito-ku, TOKYO, 110 JAPAN

Block Diagram



A01587

Pin Assignment



A01588

Pin Functions

|               |  |
|---------------|--|
| A0 to A14     | Address input                                |
| LWE           | Lower byte write enable Input                |
| UWE           | Upper byte write enable Input                |
| LOE/RFSH      | Lower byte output enable Input/refresh Input |
| UOE           | Upper byte output enable Input               |
| CE            | Chip enable input                            |
| I/O1 to I/O8  | Lower byte data input/output                 |
| I/O9 to I/O16 | Upper byte data input/output                 |
| VCC           | Power supply                                 |
| GND           | Ground                                       |

## Functional Logic

| CE | LOE/RFSH | UOE | LWE | UWE | A0 to A7 | A8 to A14 | I/O1 to I/O8 | I/O9 to I/O16 | State              |
|----|----------|-----|-----|-----|----------|-----------|--------------|---------------|--------------------|
| H  | H        | X   | X   | X   | X        | X         | HZ           | HZ            | Standby            |
| L  | L        | L   | H   | H   | VX       | VX        | OUT          | OUT           | Read (word)        |
| L  | L        | H   | H   | H   | VX       | VX        | OUT          | HZ            | Read (lower byte)  |
| L  | H        | L   | H   | H   | VX       | VX        | HZ           | OUT           | Read (upper byte)  |
| L  | H        | H   | L   | L   | VX       | VX        | IN           | IN            | Write (word)       |
| L  | H        | H   | L   | H   | VX       | VX        | IN           | HZ            | Write (lower byte) |
| L  | H        | H   | H   | L   | VX       | VX        | HZ           | IN            | Write (upper byte) |
| L  | H        | H   | H   | H   | VX       | X         | HZ           | HZ            | CE-only refresh    |
| H  | NP       | X   | X   | X   | X        | X         | HZ           | HZ            | Auto-refresh       |

H: High-level input of  $V_{IN} = 6.5\text{ V}$  to  $V_{IH}$  (min)

L: Low-level input of  $V_{IN} = V_{IL}$  (max) to  $-1.0\text{ V}$

X: High- or low-level input

NP: Negative-polarity pulse input

VX: "IN" when  $CE = L$  is confirmed, then "X"

HZ: High impedance

IN: Input state

OUT: Output state

## Specifications

## Absolute Maximum Ratings

| Parameter                   | Symbol              | Ratings          | Unit               | Note |
|-----------------------------|---------------------|------------------|--------------------|------|
| Maximum supply voltage      | $V_{CC\text{ max}}$ | $-1.0$ to $+7.0$ | V                  | 1    |
| Input voltage               | $V_{IN}$            | $-1.0$ to $+7.0$ | V                  | 1    |
| Output voltage              | $V_{OUT}$           | $-1.0$ to $+7.0$ | V                  | 1    |
| Allowable power dissipation | $P_{d\text{ max}}$  | 600              | mW                 | 1    |
| Output short current        | $I_{OUT}$           | 50               | mA                 | 1    |
| Operating temperature range | $T_{opr}$           | 0 to $+70$       | $^{\circ}\text{C}$ | 1    |
| Storage temperature range   | $T_{stg}$           | $-55$ to $+150$  | $^{\circ}\text{C}$ | 1    |

Note: 1. Stresses greater than the above listed maximum values may result in damage to the device.

DC Recommended Operating Ranges at  $T_a = 0$  to  $+70^{\circ}\text{C}$ 

| Parameter                | Symbol   | min    | typ | max  | Unit | Note |
|--------------------------|----------|--------|-----|------|------|------|
| Power supply voltage     | $V_{CC}$ | 4.5    | 5.0 | 5.5  | V    | 2    |
| Input high level voltage | $V_{IH}$ | 2.4    |     | 6.5  | V    | 2    |
| Input low level voltage  | $V_{IL}$ | $-1.0$ |     | +0.8 | V    | 2    |

Note: 2. All voltages are referenced to GND.

DC Electrical Characteristics at  $T_a = 0$  to  $+70^{\circ}\text{C}$ ,  $V_{CC} = 5\text{V} \pm 10\%$ 

| Parameter   | Symbol     | Conditions   | min         | max    | Unit          | Note |      |
|---|------------|--|-------------|--------|---------------|------|------|
| Operating current<br>(Average current during operation) | $I_{CCA}$  | $t_{RC} = t_{RC}(\text{min})$  | Access time | 70 ns  | 100           | mA   | 3, 4 |
|   |            |  |             | 80 ns  | 90            |      |      |
|   |            |  |             | 100 ns | 75            |      |      |
|   |            |  |             | 120 ns | 65            |      |      |
| Standby current 1                                       | $I_{CCS1}$ | $\overline{CE} = \overline{LOE/RFSH} = V_{IH}$                             |             | 3      | mA            |      |      |
| Standby current 2                                       | $I_{CCS2}$ | $\overline{CE} = \overline{LOE/RFSH} = V_{CC} - 0.2\text{ V}$              |             | 2      | mA            |      |      |
| Input leakage current                                   | $I_{IL}$   | $0\text{ V} \leq V_{IN} \leq V_{CC}$ , pins other than measuring pin = 0 V | -10         | +10    | $\mu\text{A}$ |      |      |
| Output leakage current                                  | $I_{OL}$   | Output disable, $0\text{ V} \leq V_{OUT} \leq V_{CC}$                      | -10         | +10    | $\mu\text{A}$ |      |      |
| Output high level voltage                               | $V_{OH}$   | $I_{OUT} = -1\text{ mA}$   | 2.4         |        | V             |      |      |
| Output low level voltage                                | $V_{OL}$   | $I_{OUT} = 4.2\text{ mA}$  |             | 0.4    | V             |      |      |

Note: 3. All current values are measured at minimum cycle rate. Since current flows immoderately, if cycle time is longer than shown here, current value becomes smaller. A bypass capacitor of  $0.01\text{ }\mu\text{F}$  or larger should be inserted between  $V_{CC}$  and GND for each memory chip to suppress power supply noise (voltage drops) due to transient currents.

4. Dependent on output load. Maximum value is value during free state.

**Input/Output Capacitance Characteristics at Ta = 25°C, f = 1 MHz, VCC = 5 V ± 10%**

| Parameter                                       | Symbol           | Measuring Conditions   | min | max | Unit |
|---|------------------|------------------------|-----|-----|------|
| Input capacitance (A0 to A14)                   | C <sub>IN1</sub> | V <sub>IN1</sub> = 0 V |     | 5   | pF   |
| Input capacitance (CE, LOE/RFSH, UOE, LWE, UWE) | C <sub>IN2</sub> | V <sub>IN2</sub> = 0 V |     | 7   | pF   |
| I/O capacitance                                 | C <sub>I/O</sub> | V <sub>I/O</sub> = 0 V |     | 10  | pF   |

Sampling inspections, and not full-lot inspections, are carried out for these parameters.

**AC Electrical Characteristics at Ta = 0 to +70°C, VCC = 5 V ± 10% (Notes 5, 6, 7, 8, 9)**

| Parameter                                | Symbol           | -70 |       | -80 |       | -10 |       | -12 |       | Unit | Note |
|--|------------------|-----|-------|-----|-------|-----|-------|-----|-------|------|------|
|  |                  | min | max   | min | max   | min | max   | min | max   |      |      |
| Random read or write cycle time          | t <sub>RC</sub>  | 115 |       | 130 |       | 160 |       | 210 |       | ns   |      |
| CE pulse width                           | t <sub>CE</sub>  | 70  | 10000 | 80  | 10000 | 100 | 10000 | 120 | 10000 | ns   |      |
| CE precharge time                        | t <sub>P</sub>   | 35  |       | 40  |       | 50  |       | 80  |       | ns   |      |
| CE access time                           | t <sub>CEA</sub> |     | 70    |     | 80    |     | 100   |     | 120   | ns   |      |
| LOE, UOE access time                     | t <sub>OEA</sub> |     | 35    |     | 40    |     | 50    |     | 75    | ns   |      |
| CE output enable time                    | t <sub>CLZ</sub> | 10  |       | 10  |       | 10  |       | 10  |       | ns   |      |
| LOE, UOE output enable time              | t <sub>OLZ</sub> | 0   |       | 0   |       | 0   |       | 0   |       | ns   |      |
| CE output disable time                   | t <sub>CHZ</sub> | 0   | 20    | 0   | 25    | 0   | 30    | 0   | 35    | ns   | 10   |
| LOE, UOE output disable time             | t <sub>OHZ</sub> | 0   | 20    | 0   | 25    | 0   | 30    | 0   | 35    | ns   | 10   |
| LOE, UOE hold time for CE                | t <sub>OHC</sub> | 0   |       | 0   |       | 0   |       | 0   |       | ns   |      |
| LOE, UOE setup time for CE               | t <sub>OSC</sub> | 10  |       | 10  |       | 10  |       | 10  |       | ns   |      |
| Read command setup time                  | t <sub>RCS</sub> | 0   |       | 0   |       | 0   |       | 0   |       | ns   |      |
| Read command hold time                   | t <sub>RCH</sub> | 0   |       | 0   |       | 0   |       | 0   |       | ns   |      |
| Write pulse width                        | t <sub>WP</sub>  | 25  |       | 30  |       | 35  |       | 85  |       | ns   |      |
| Write command hold time                  | t <sub>WCH</sub> | 55  |       | 60  |       | 65  |       | 85  |       | ns   |      |
| Write command lead time                  | t <sub>CWL</sub> | 40  |       | 45  |       | 50  |       | 85  |       | ns   |      |
| Input data setup time for LWE, UWE       | t <sub>DSW</sub> | 25  |       | 30  |       | 35  |       | 50  |       | ns   | 11   |
| Input data setup time for CE             | t <sub>DSC</sub> | 25  |       | 30  |       | 35  |       | 50  |       | ns   | 11   |
| Input data hold time for LWE, UWE        | t <sub>DHW</sub> | 0   |       | 0   |       | 0   |       | 0   |       | ns   | 11   |
| Input data hold time for CE              | t <sub>DHC</sub> | 0   |       | 0   |       | 0   |       | 0   |       | ns   | 11   |
| Address setup time for CE                | t <sub>ASC</sub> | 0   |       | 0   |       | 0   |       | 0   |       | ns   | 12   |
| Address hold time for CE                 | t <sub>AHC</sub> | 15  |       | 20  |       | 25  |       | 30  |       | ns   | 12   |
| Auto-refresh cycle time                  | t <sub>FC</sub>  | 115 |       | 130 |       | 160 |       | 210 |       | ns   |      |
| RFSH delay time for CE                   | t <sub>RFD</sub> | 35  |       | 40  |       | 50  |       | 60  |       | ns   |      |
| RFSH pulse width (Auto-refresh)          | t <sub>FAP</sub> | 75  | 8000  | 80  | 8000  | 80  | 8000  | 80  | 8000  | ns   | 13   |
| RFSH precharge time (Auto-refresh)       | t <sub>FP</sub>  | 30  |       | 30  |       | 30  |       | 30  |       | ns   | 13   |
| RFSH active CE delay time (Auto-Refresh) | t <sub>FCE</sub> | 135 |       | 160 |       | 190 |       | 225 |       | ns   | 13   |
| Refresh time                             | t <sub>REF</sub> |     | 4     |     | 4     |     | 4     |     | 4     | ms   |      |
| Rise or fall time                        | t <sub>T</sub>   | 3   | 50    | 3   | 50    | 3   | 50    | 3   | 50    | ns   |      |

Note: 5. To accomplish internal initialization, CE and LOE/RFSH are fixed at V<sub>IH</sub> for an interval of 1 ms when V<sub>CC</sub> reaches the specified voltage after power is switched on. At least eight dummy cycles must be executed following that period.

6. Measured at t<sub>T</sub> = 5 ns.

7. When measuring input signal timing, V<sub>IH</sub> (min) and V<sub>IL</sub> (max) are reference levels.

8. Measured using an equivalent of 100 pF and two standard TTL loads.

9. LOE/RFSH input functions as lower byte output enable input (LOE) when CE = V<sub>IL</sub>, and as refresh input (RFSH) when CE = V<sub>IH</sub>.

10. t<sub>CHZ</sub> and t<sub>OHZ</sub> are defined as the time until output enters the open circuit state and the output voltage level becomes immeasurable.

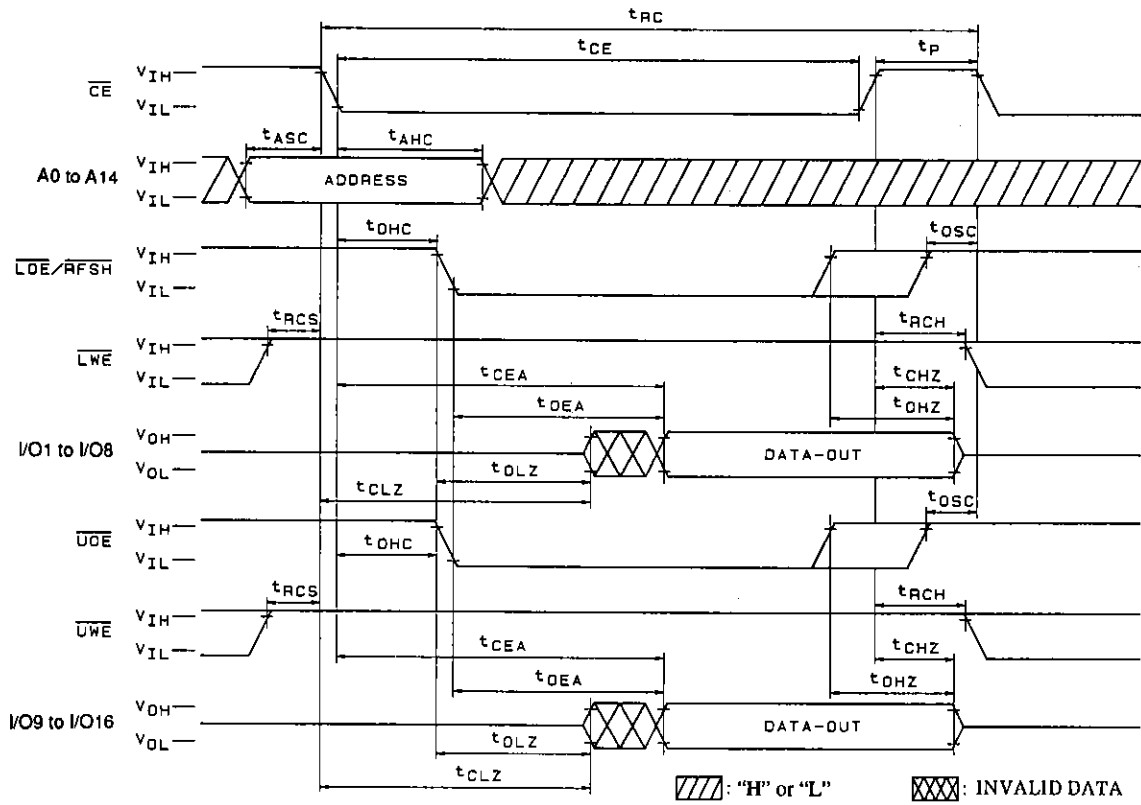
11. As with ordinary static RAM, write data is incorporated at the rise of LWE, UWE input or CE input, whichever is earlier, and write data is therefore held during t<sub>DSW</sub>, t<sub>DSC</sub>, t<sub>DHW</sub>, or t<sub>DHC</sub>.

12. Because address input is incorporated at the fall of CE, the address is maintained during t<sub>ASC</sub> or t<sub>AHC</sub>.

13. After auto-refresh has completed, CE must not be made active until the t<sub>FCE</sub> period has elapsed.

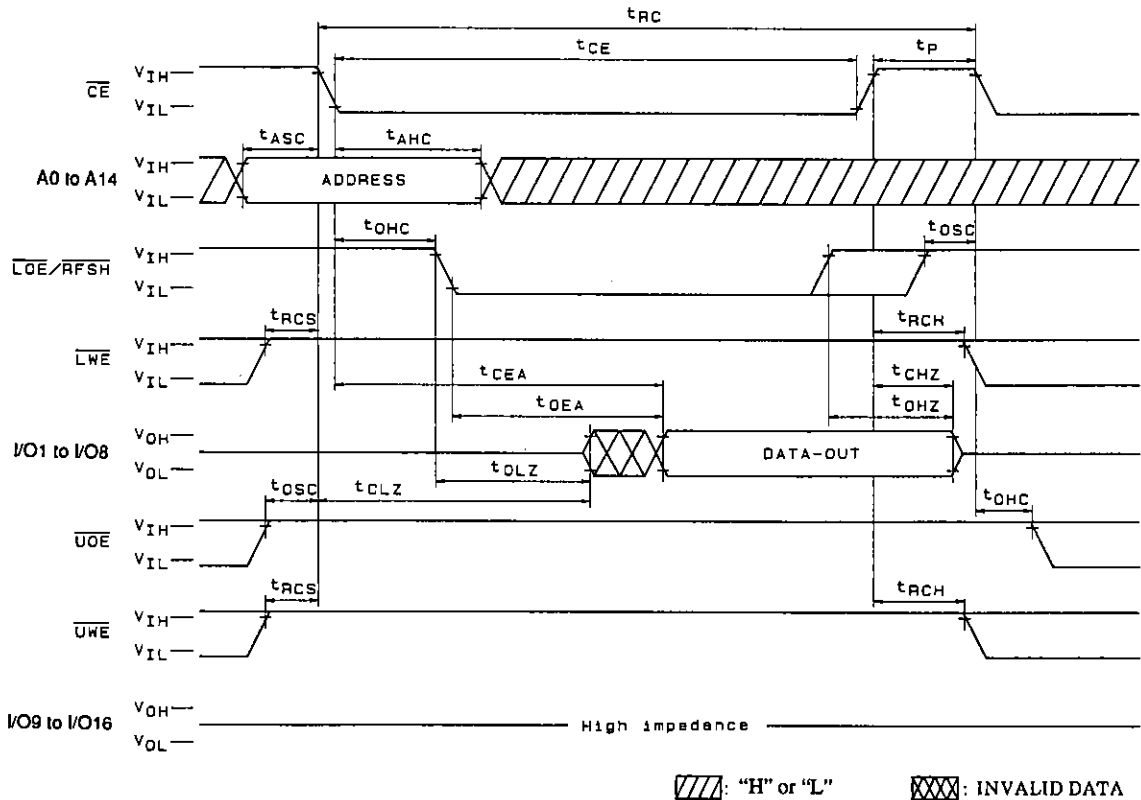
Timing Chart

Read Cycle (word)



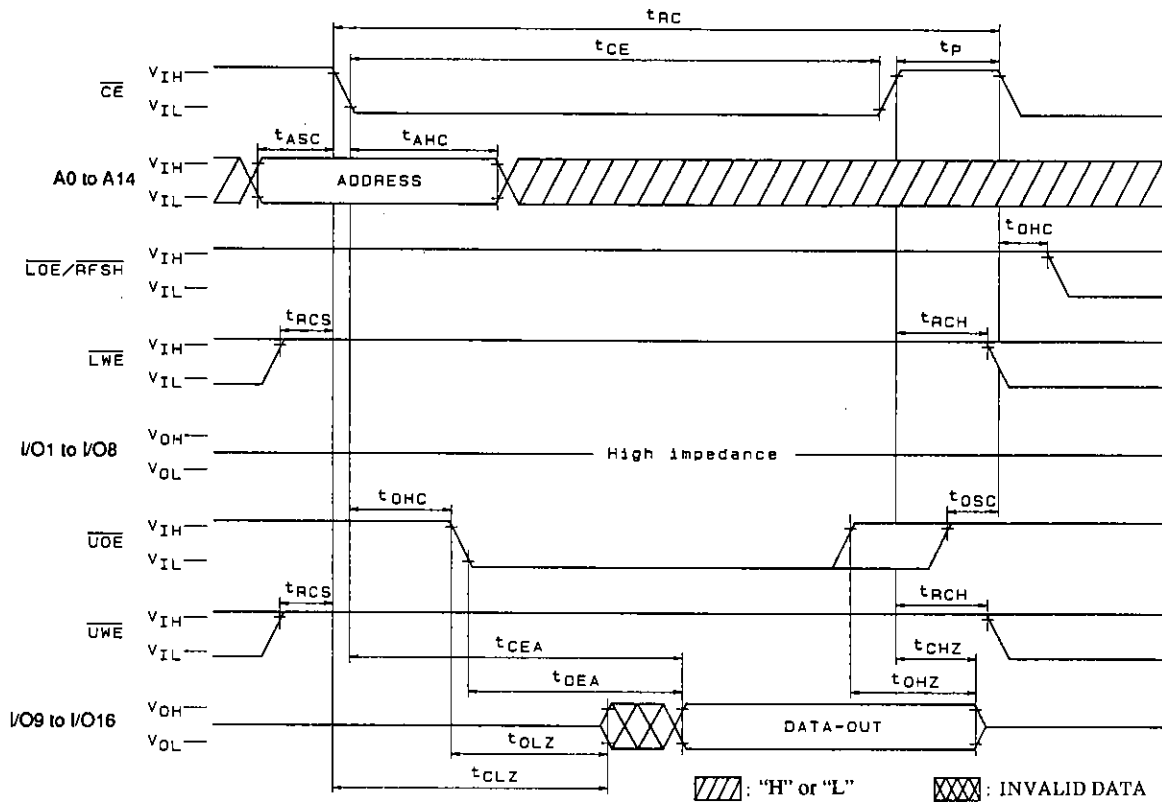
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Read Cycle (lower byte)



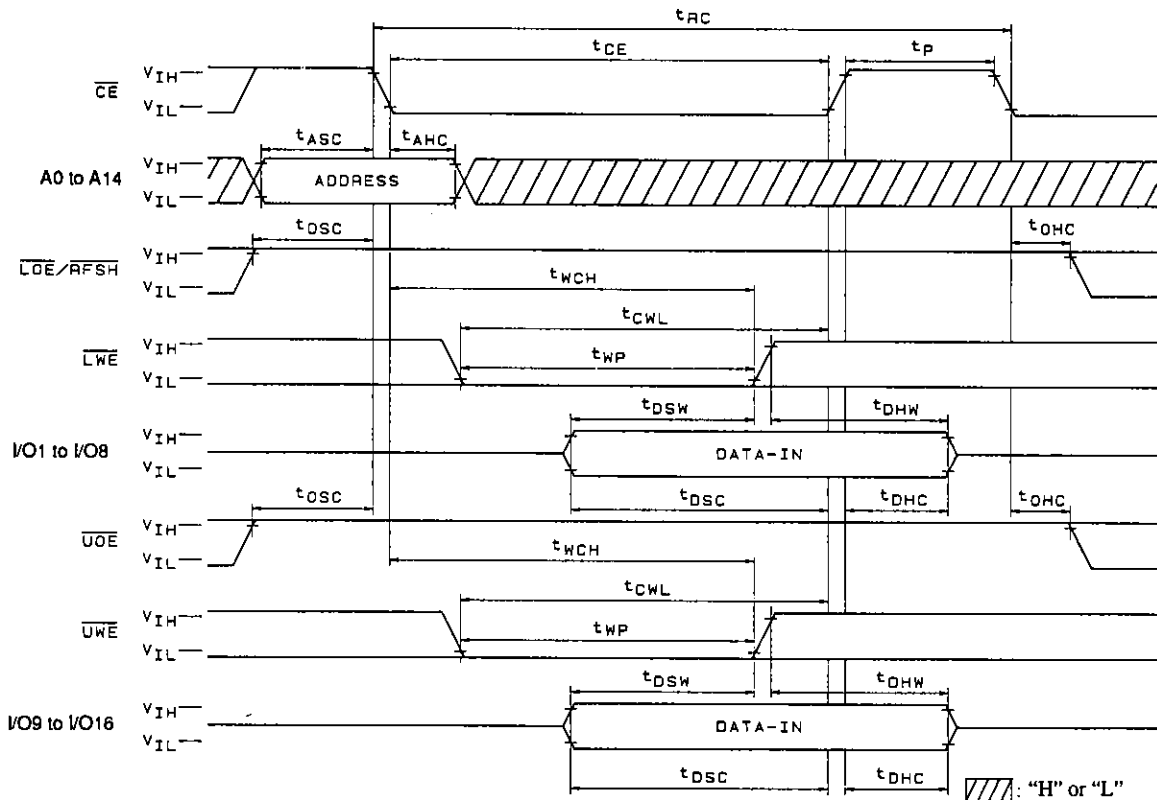
A01590

Read Cycle (upper byte)



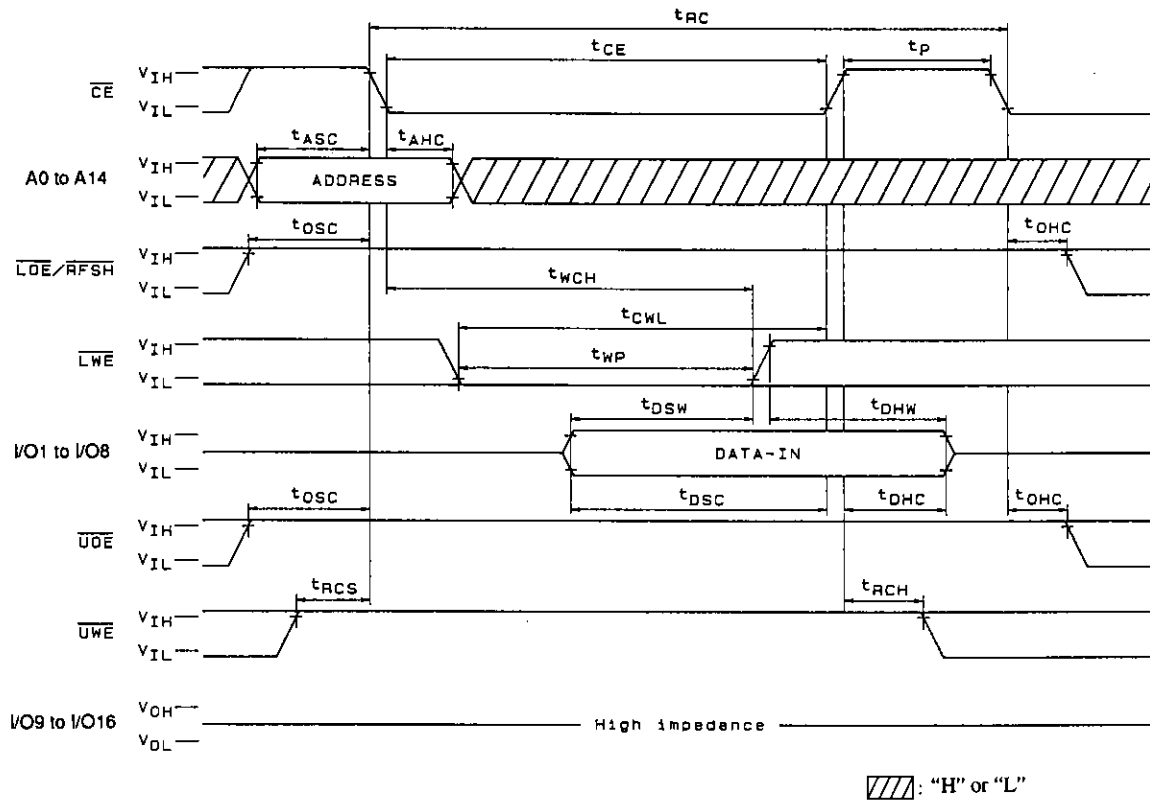
A01591

Write Cycle (word)



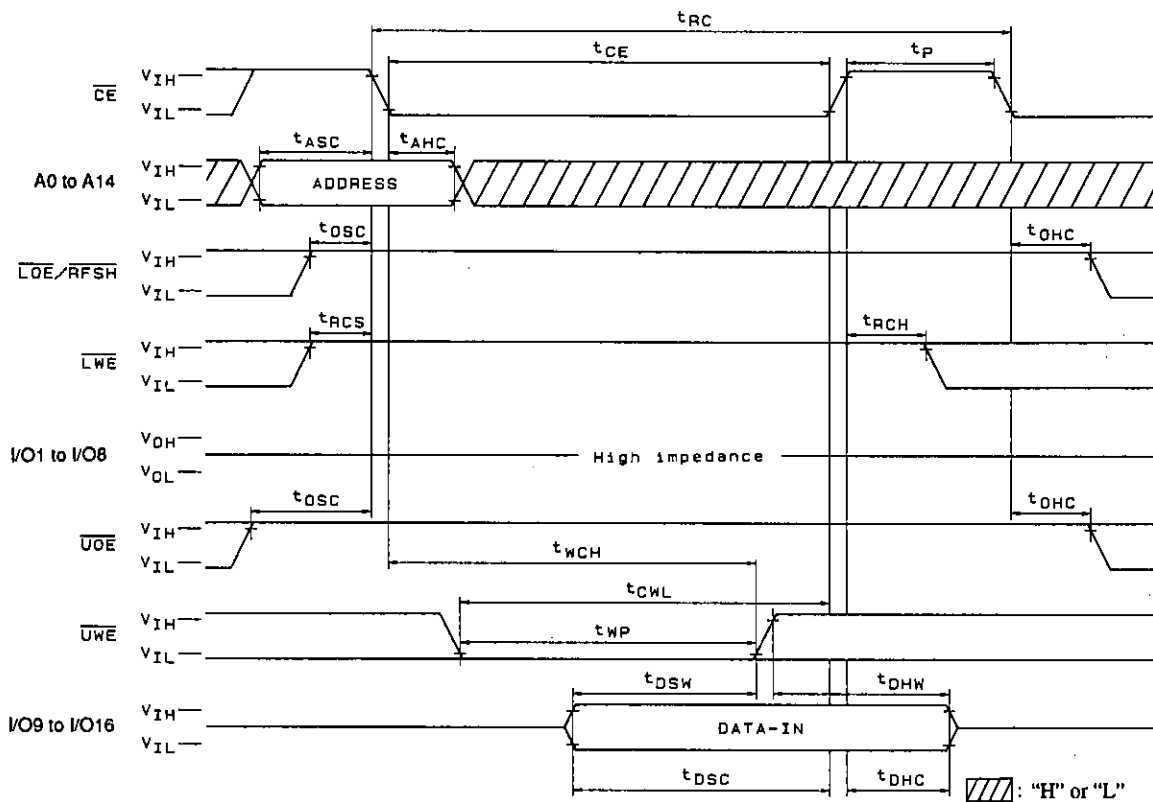
A01592

Write Cycle (lower byte)



A01593

Write Cycle (upper byte)



A01594





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